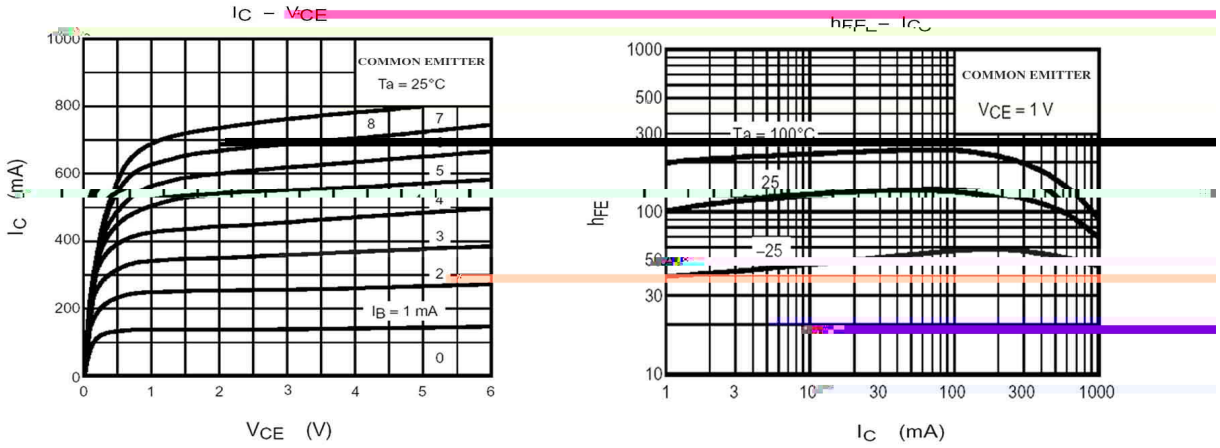
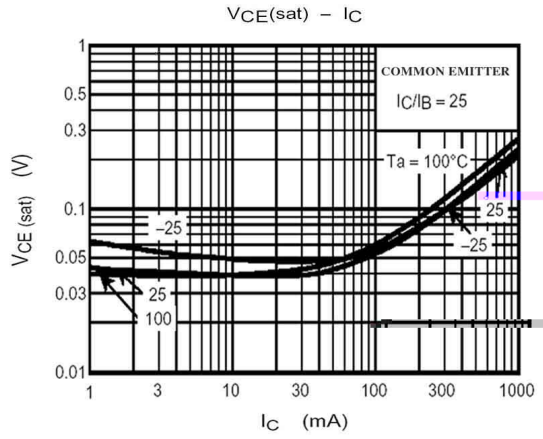
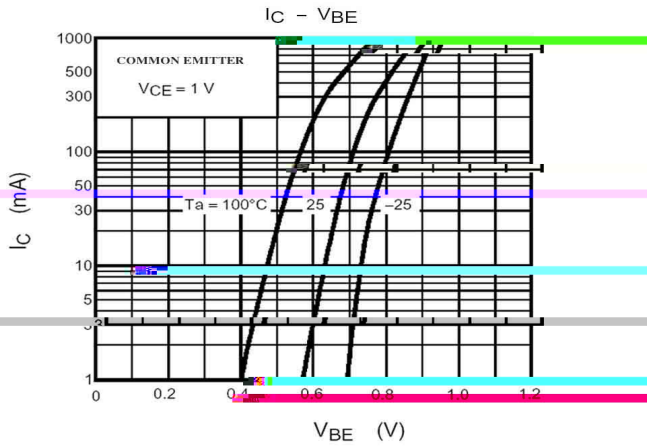
v ̈Ọ Parameter	↿ N Symbol	̈Ọ Ö Rating	D Ꮋ Unit
Collector to Base Voltage	V_{CBO}	35	V
Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	800	mA
Emitter Current - Continuous	I_E	-800	mA
Collector Power Dissipation	P_C	600	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

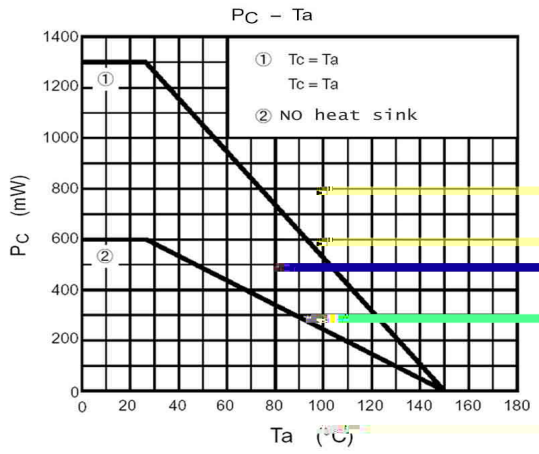
v ̈Ọ Parameter	↿ N Symbol	⅄ ; ̇ Ţ Test Conditions	ѡ ṇ Ö Min	Ɛ ȝ Ö Typ	ѡ ᶻ Ö Max	D Ꮋ Unit
Collector to Base Breakdown Voltage	V_{CBO}	I_C=10mA I_E=0	30			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=35V I_E=0			0.1	μA
Emitter Cut-Off Current	I_{EBO}	V_{EB}=5.0V I_C=0			0.1	μA
DC Current Gain	$h_{FE(1)}$	V_{CE}=1.0V I_C=100mA	100		320	
	$h_{FE(2)}$	V_{CE}=1.0V I_C=700mA	35			

/ Electrical Characteristic Curve

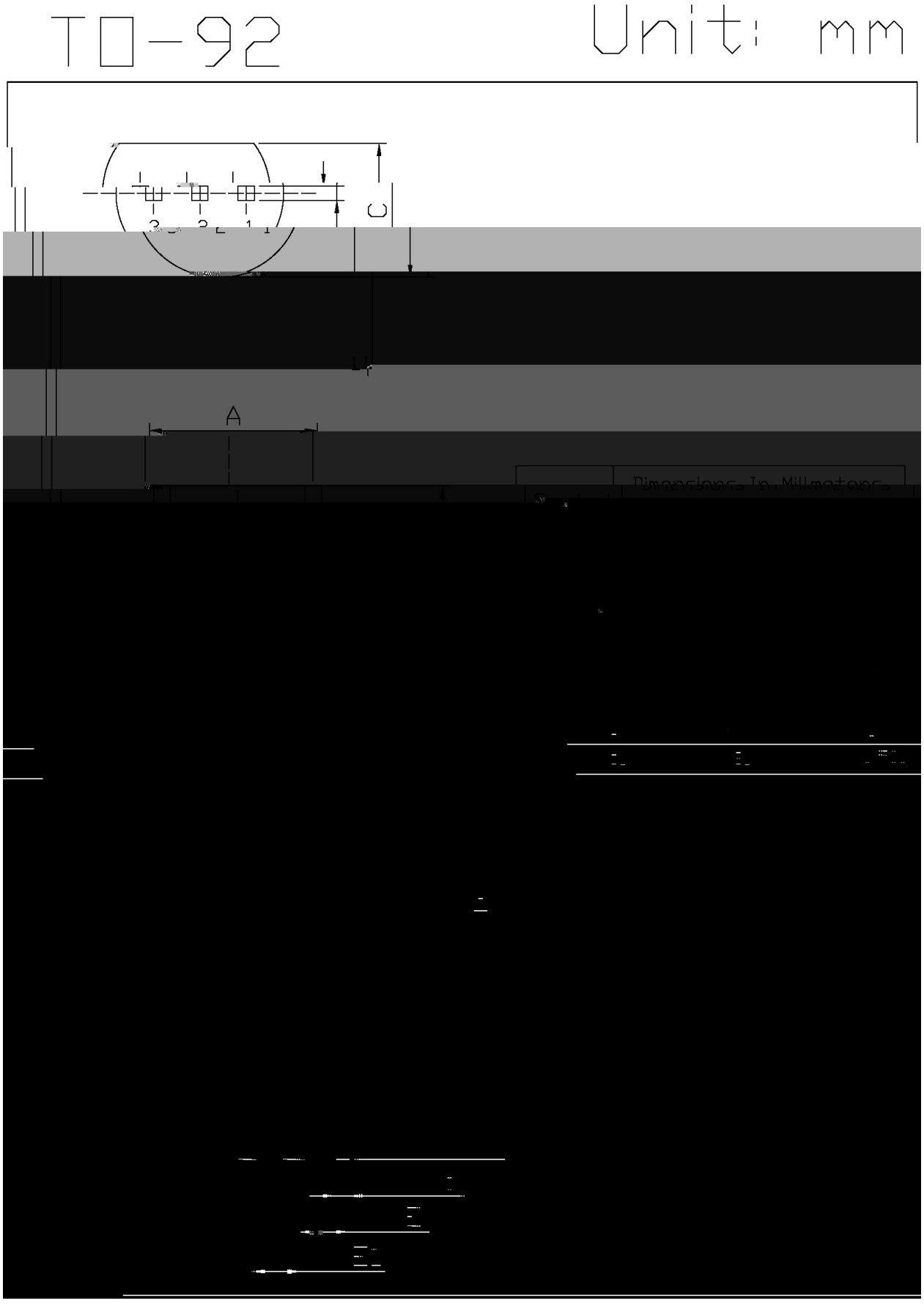


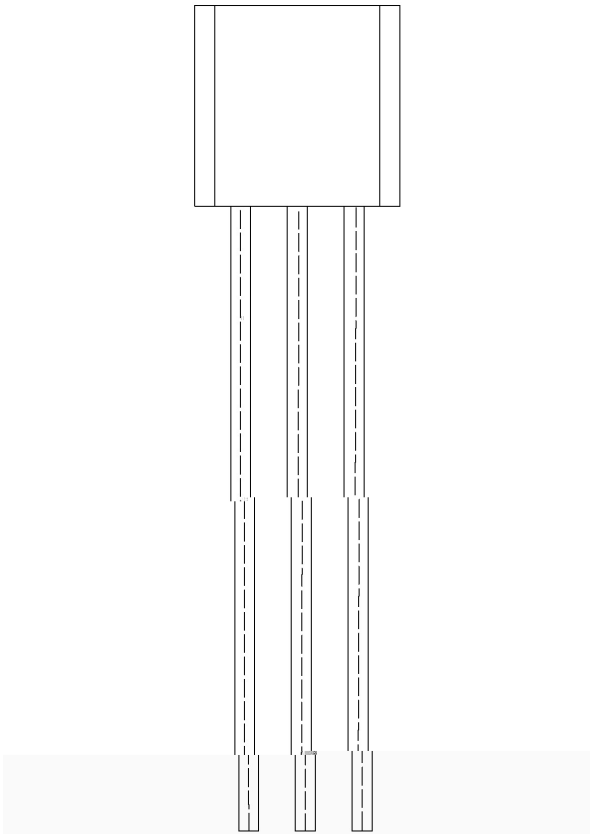




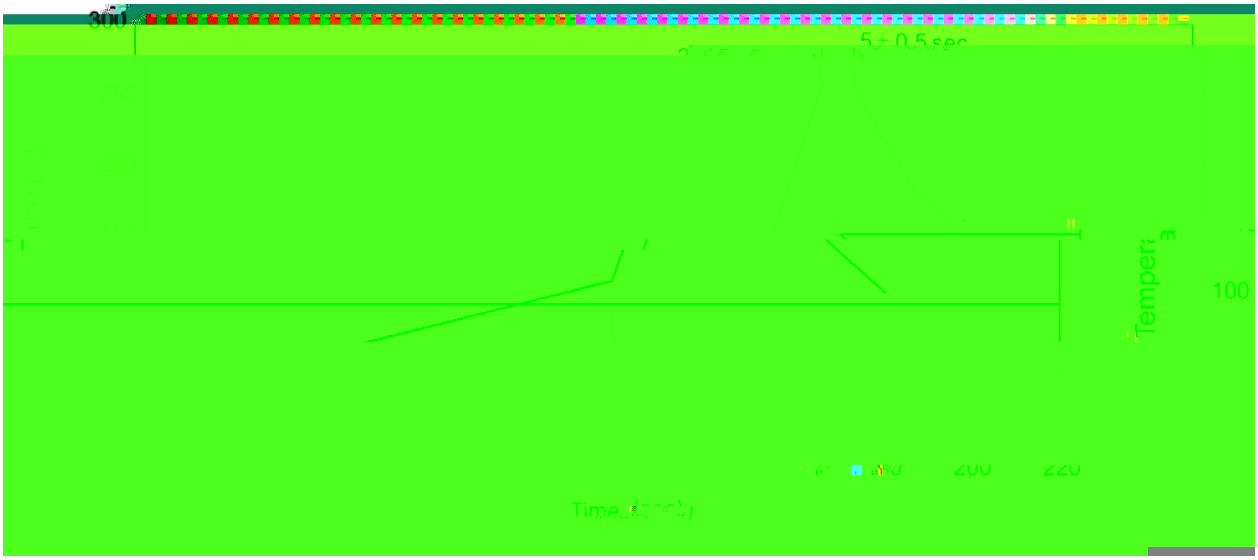


/ Package Dimensions





( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı ˋH ڑ 60 Ḱ 90sec;

2 Š Ө □ ỷ 255 ° 5 ł ı ˋH ڑ ˋY ﾊ ㎛ 5 ° 0.5sec;

3 ì ˙ ﾘ ˛ ɔ ෯ ỷ ㎛ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ł	ˋH ڑ χ 10 ° 1 sec.	Temp:270±5	Time:10±1 sec

/ Packaging SPEC.

ˈQ ţ ﾔ Ł / BULK

Package Type	Units	Dimension	(unit mm3)